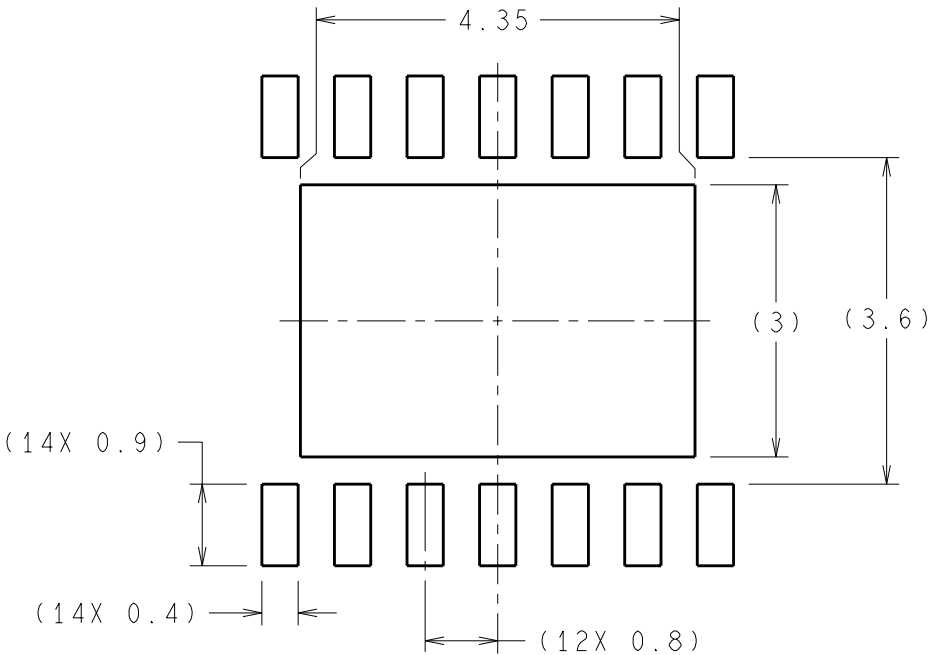
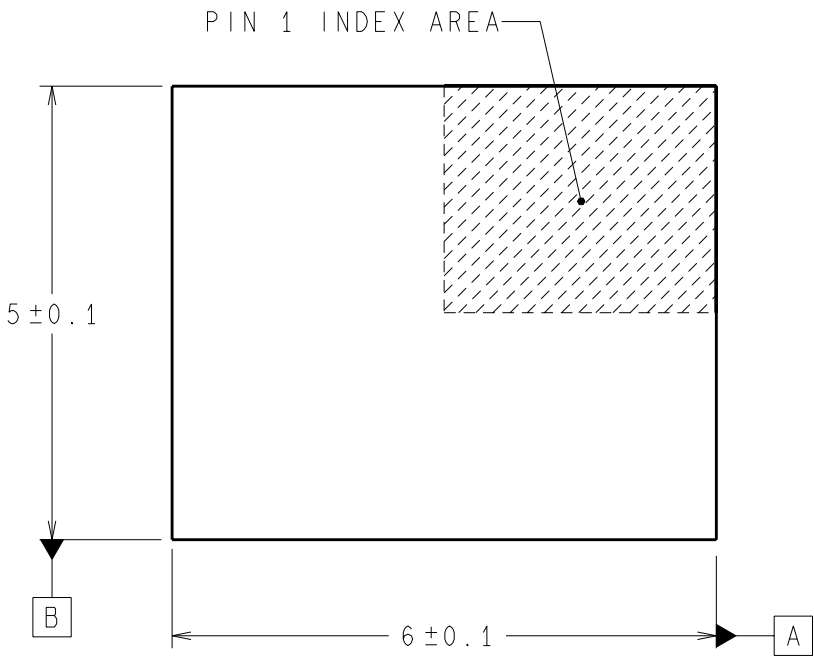


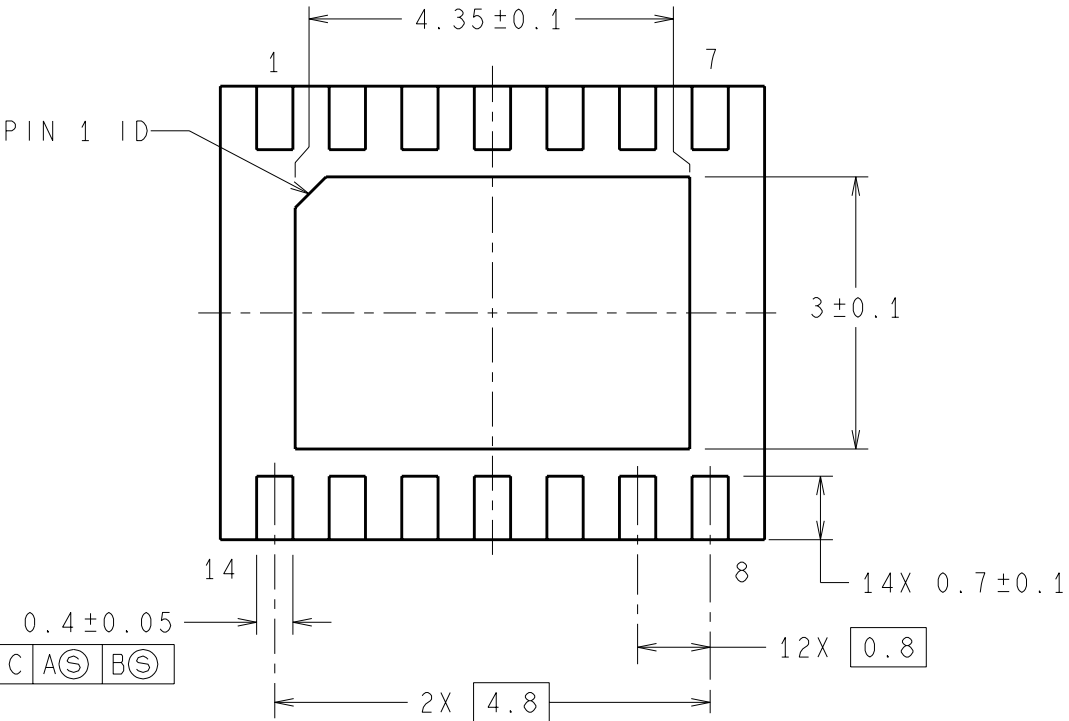
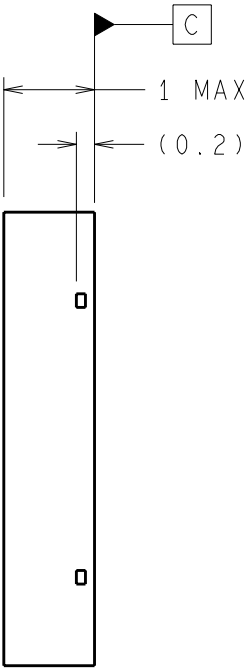
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	939	03/28/2003	LY/TL/SN



RECOMMENDED LANDED PATTERN
1:1 RATIO WITH PKG SOLDER PADS

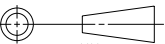


DIMENSIONS ARE IN MILLIMETERS



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com)
- METAL BURR ON LEADS IS 40 MICROMETERS MAXIMUM.
- NO JEDEC REGISTRATION AS OF MARCH 2003.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090		POWER LLP, PLASTIC, DUAL, 6x5x1.0mm BODY, 14 LD, 0.8mm PITCH, EXT LD	
DRAWN	LYE MENG KONG	03/28/2003				
DFTG. CHK.	THANH LEQUANG	03/28/2003	NTS		B	
ENGR. CHK.	N. SANTHIRAN	03/28/2003				
		SCALE NTS	SIZE B	DRAWING NUMBER (SC)MKT-LDN14A	REV A	SHEET 1 of 1